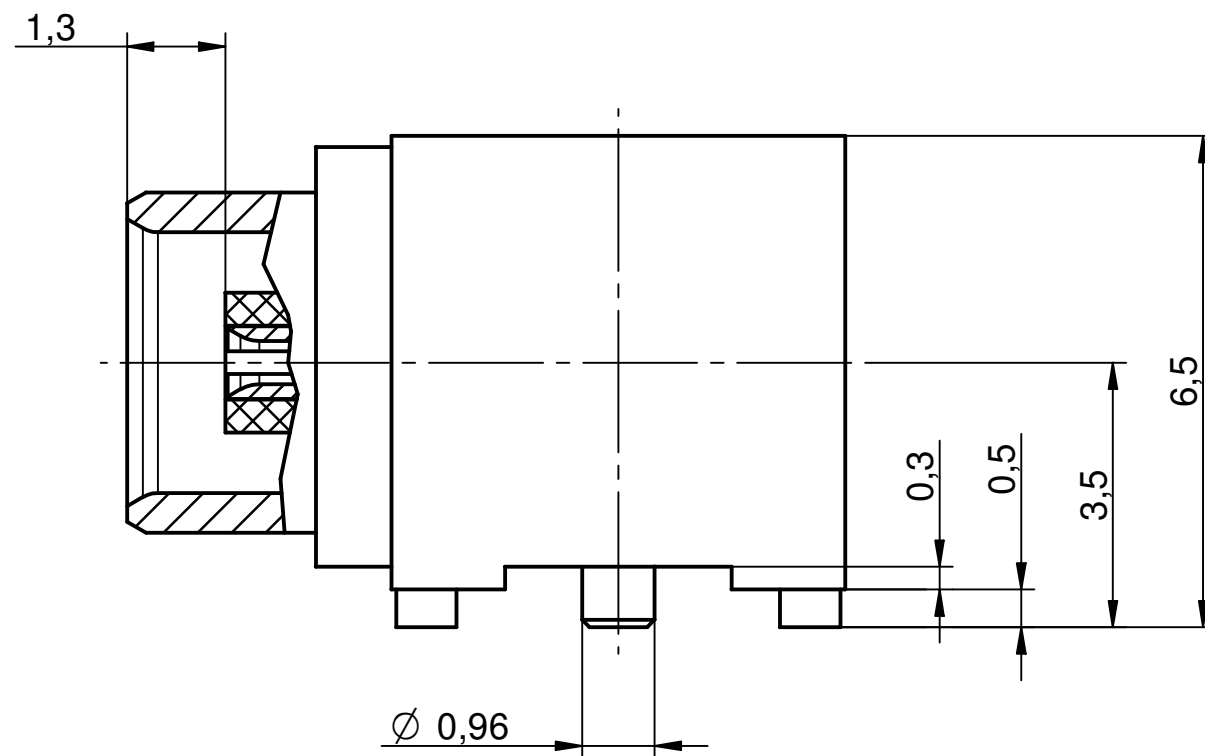
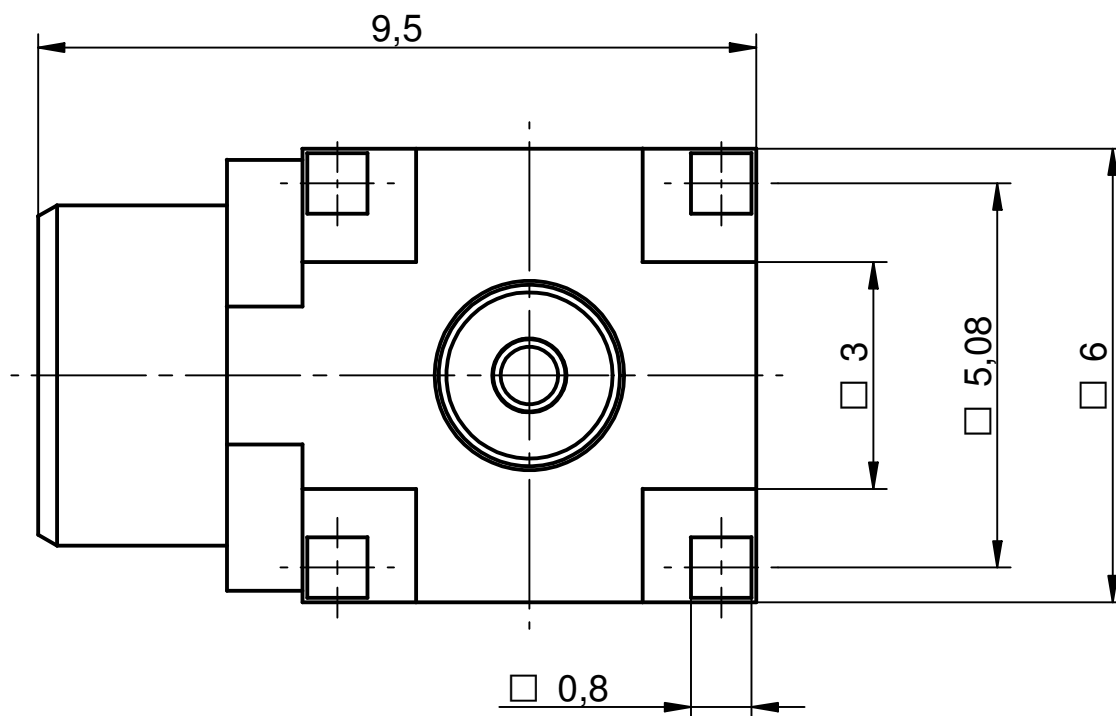
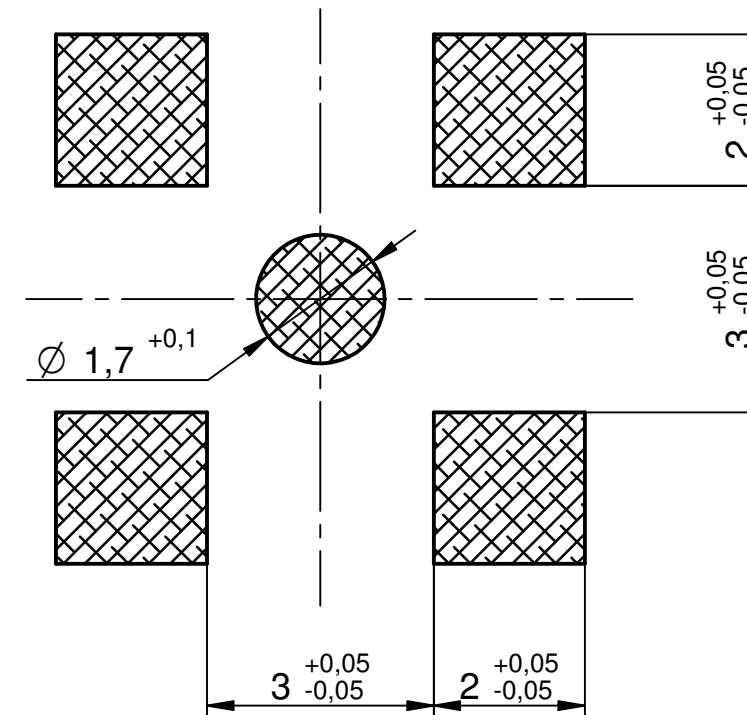


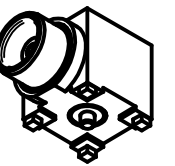


- 1.) Steckkraft mit Stecker
Mating force with plug
min. 5N - max. 12N
- 2.) Abzugskraft mit Stecker
Separating force with plug
min. 10N - max. 20N

SMD-Lötflächen Solderpad layout



M/s 2:1



M/s 1:1



Verpackung:

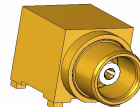
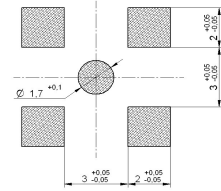
Blistergurt: AGK-4245
83,3Stk/m
Gurtlänge: ca. 10m
Spulen Durchmesser: 330mm
750 Teile pro Gurt
Abdeckband:1010368
Vorlauf: 400mm
Nachlauf: 400mm

Packaging:

Tape and reel: AGK-4245
83,3 pcs/m
tapelenght: app. 10m
reeldiameter: 330mm
750 parts per reel
Covertape:1010368
forward run: 400mm
after run: 400mm

					general tolerance ISO 2768 mH angle: ± 5°		scale: 10:1	
					date		name	
					generate		Pölz	
					checked			
					Norm			

Product data sheet

Part Number: 4752.01.2520.003		Revision: -
Description: Anbauwinkelbuchse		Date: 25.10.2010
		Signature: A.Varga
		Page: 1 of 2
Design according to:	IEC 1169-36 / CECC 22220 (Type MCX)	
Electrical characteristics:	colored value means: still under test target value	
	Value	Unit
Impedance (MIL-C- 39012B)	50	[Ω]
Operating frequency up to	6	[GHz]
Return loss	-	-
1 GHz	27	[dB]
2 GHz	24	[dB]
4 GHz	21	[dB]
6 GHz	16	[dB]
10 GHz	-	[dB]
18 GHz	-	[dB]
3rd. Order PIM product 2x43dBm	/	[dBc]
Insulation resistance	10	[GΩ]
Contact resistance		
Centre contact	5	[mΩ]
Outer contact	1	[mΩ]
Contact current max. (DC)	1,5	[A]
Operating voltage	170	[V]
Proof voltage	500	[V]
		Picture
		
		Remarks
		SMD-LOETFLACHEN SOLDERPAD LAYOUT
		
Mechanical characteristics:	Value	Unit
Engagement force	Max. 25	[N]
Separating force	Min. 8 - Max. 20	[N]
Mating cycles	> 500	

Tel (+99) 7654 901-0
Fax (+99) 7654 901-199
Net: www.imsccs.com
E-mail: sales@imsccs.com

Part Number: 4752.01.2520.003						Revision: -	
						Date: 25.10.2010	
Description: Anbauwinkelbuchse						Signature: A.Varga	
						Page: 2 of 2	
<u>Material & plating:</u> Outer contact Centre contact Guiding ferrule Insulator				RoHS (2002/95/EC) conform			
				Material		Plating	
				Brass		Ni + Ni-P + 0,15µm Au	
				Copper beryllium		Ni-P + 0,15µm Au	
				Brass		Ni-P + 0,15µm Au	
				PTFE		-	
<u>Environmental influences:</u> Operating temperature range Climatic sequence: 1. Dry heat 2. Damp heat, cyclic, 1 cycle 3. Cold 4. Damp heat, cyclic, 6 cycles Solder profile:						Remarks	
				-55°C up to +125°C			
				Standard			
				IEC 60068-2-61		Var. 1	
				IEC 60068-2-2-Ba		85°C / 16h	
				IEC 60068-2-30-Db		Var. 1, upper temp: 55°C	
				IEC 60068-2-1-Aa		-25°C / 2h	
				IEC 60068-2-30-Db		Var. 1, upper temp: 55°C	
				Jedec 020 D			
<u>Notes:</u>							
<u>Update historie</u>							
Rev.	Date	Alteration	Signature				
Formblatt-Nr.: Form-TK-012b							